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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, LCD, POR, PWM, WDT
Number of I/O	66
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f8490-i-pt

TABLE 1-2: PIC18F6X90 PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
$\overline{MCLR}$/VPP/RG5	7			Master Clear (input) or programming voltage (input).
$\overline{MCLR}$		I	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
VPP		P		Programming voltage input.
RG5		I	ST	Digital input.
OSC1/CLKI/RA7	39			Oscillator crystal or external clock input.
OSC1		I	ST	Oscillator crystal input or external clock source input. ST buffer when configured in RC mode, CMOS otherwise.
CLKI		I	CMOS	External clock source input. Always associated with pin function OSC1. (See related OSC1/CLKI, OSC2/CLKO pins.)
RA7		I/O	TTL	General purpose I/O pin.
OSC2/CLKO/RA6	40			Oscillator crystal or clock output.
OSC2		O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode.
CLKO		O	—	In RC mode, OSC2 pin outputs CLKO, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
RA6		I/O	TTL	General purpose I/O pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to VDD)

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8X90 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT0	58			
RB0		I/O	TTL	Digital I/O.
INT0		I	ST	External interrupt 0.
RB1/INT1/SEG8	57			
RB1		I/O	TTL	Digital I/O.
INT1		I	ST	External interrupt 1.
SEG8		O	Analog	SEG8 output for LCD.
RB2/INT2/SEG9	56			
RB2		I/O	TTL	Digital I/O.
INT2		I	ST	External interrupt 2.
SEG9		O	Analog	SEG9 output for LCD.
RB3/INT3/SEG10	55			
RB3		I/O	TTL	Digital I/O.
INT3		I	ST	External interrupt 3.
SEG10		O	Analog	SEG10 output for LCD.
RB4/KBI0/SEG11	54			
RB4		I/O	TTL	Digital I/O.
KBI0		I	TTL	Interrupt-on-change pin.
SEG11		O	Analog	SEG11 output for LCD.
RB5/KBI1	53			
RB5		I/O	TTL	Digital I/O.
KBI1		I	TTL	Interrupt-on-change pin.
RB6/KBI2/PGC	52			
RB6		I/O	TTL	Digital I/O.
KBI2		I	TTL	Interrupt-on-change pin.
PGC		I/O	ST	In-Circuit Debugger and ICSP™ programming clock pin.
RB7/KBI3/PGD	47			
RB7		I/O	TTL	Digital I/O.
KBI3		I	TTL	Interrupt-on-change pin.
PGD		I/O	ST	In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to V_{DD})

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

REGISTER 4-1: RCON: RESET CONTROL REGISTER

R/W-0	R/W-1(1)	U-0	R/W-1	R-1	R-1	R/W-0	R/W-0
IPEN	SBOREN	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IPEN:** Interrupt Priority Enable bit
1 = Enable priority levels on interrupts
0 = Disable priority levels on interrupts (PIC16CXXX Compatibility mode)

bit 6 **SBOREN:** BOR Software Enable bit(1)
If BOREN1:BOREN0 = 01:
1 = BOR is enabled
0 = BOR is disabled
If BOREN1:BOREN0 = 00, 10 or 11:
Bit is disabled and read as '0'.

bit 5 **Unimplemented:** Read as '0'

bit 4 **$\overline{RI}$:** RESET Instruction Flag bit
1 = The RESET instruction was not executed (set by firmware only)
0 = The RESET instruction was executed causing a device Reset (must be set in software after a Brown-out Reset occurs)

bit 3 **$\overline{TO}$:** Watchdog Time-out Flag bit
1 = Set by power-up, CLRWDT instruction or SLEEP instruction
0 = A WDT time-out occurred

bit 2 **$\overline{PD}$:** Power-Down Detection Flag bit
1 = Set by power-up or by the CLRWDT instruction
0 = Set by execution of the SLEEP instruction

bit 1 **$\overline{POR}$:** Power-on Reset Status bit
1 = A Power-on Reset has not occurred (set by firmware only)
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$:** Brown-out Reset Status bit
1 = A Brown-out Reset has not occurred (set by firmware only)
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

Note 1: If SBOREN is enabled, its Reset state is '1'; otherwise, it is '0'.

Note 1: It is recommended that the $\overline{POR}$ bit be set after a Power-on Reset has been detected, so that subsequent Power-on Resets may be detected.

2: Brown-out Reset is said to have occurred when $\overline{BOR}$ is '0' and $\overline{POR}$ is '1' (assuming that $\overline{POR}$ was set to '1' by software immediately after a Power-on Reset).

5.4.3.2 FSR Registers and POSTINC, POSTDEC, PREINC and PLUSW

In addition to the INDF operand, each FSR register pair also has four additional indirect operands. Like INDF, these are “virtual” registers that cannot be indirectly read or written to. Accessing these registers actually accesses the associated FSR register pair, but also performs a specific action on its stored value. They are:

- POSTDEC: accesses the FSR value, then automatically decrements it by ‘1’ afterwards
- POSTINC: accesses the FSR value, then automatically increments it by ‘1’ afterwards
- PREINC: increments the FSR value by ‘1’, then uses it in the operation
- PLUSW: adds the signed value of the W register (range of -127 to 128) to that of the FSR and uses the new value in the operation.

In this context, accessing an INDF register uses the value in the FSR registers without changing them. Similarly, accessing a PLUSW register gives the FSR value offset by the value in the W register; neither value is actually changed in the operation. Accessing the other virtual registers changes the value of the FSR registers.

Operations on the FSRs with POSTDEC, POSTINC and PREINC affect the entire register pair; that is, roll-overs of the FSRnL register from FFh to 00h carry over to the FSRnH register. On the other hand, results of these operations do not change the value of any flags in the STATUS register (e.g., Z, N, OV, etc.).

The PLUSW register can be used to implement a form of Indexed Addressing in the data memory space. By manipulating the value in the W register, users can reach addresses that are fixed offsets from pointer addresses. In some applications, this can be used to implement some powerful program control structure, such as software stacks, inside of data memory.

5.4.3.3 Operations by FSRs on FSRs

Indirect Addressing operations that target other FSRs or virtual registers represent special cases. For example, using an FSR to point to one of the virtual registers will not result in successful operations. As a specific case, assume that FSR0H:FSR0L contains FE7h, the address of INDF1. Attempts to read the value of the INDF1, using INDF0 as an operand, will return 00h. Attempts to write to INDF1, using INDF0 as the operand, will result in a NOP.

On the other hand, using the virtual registers to write to an FSR pair may not occur as planned. In these cases, the value will be written to the FSR pair, but without any incrementing or decrementing. Thus, writing to INDF2 or POSTDEC2 will write the same value to the FSR2H:FSR2L.

Since the FSRs are physical registers mapped in the SFR space, they can be manipulated through all direct operations. Users should proceed cautiously when working on these registers, particularly if their code uses Indirect Addressing.

Similarly, operations by Indirect Addressing are generally permitted on all other SFRs. Users should exercise the appropriate caution that they do not inadvertently change settings that might affect the operation of the device.

Example 7-3 shows the sequence to do a 16 x 16 unsigned multiplication. Equation 7-1 shows the algorithm that is used. The 32-bit result is stored in four registers (RES3:RES0).

EQUATION 7-1: 16 x 16 UNSIGNED MULTIPLICATION ALGORITHM

$$
\begin{aligned}
RES3:RES0 &= ARG1H:ARG1L \bullet ARG2H:ARG2L \\
&= (ARG1H \bullet ARG2H \bullet 2^{16}) + \\
&\quad (ARG1H \bullet ARG2L \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2H \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2L)
\end{aligned}
$$

EXAMPLE 7-3: 16 x 16 UNSIGNED MULTIPLY ROUTINE

```
    MOVF    ARG1L, W
    MULWF   ARG2L           ; ARG1L * ARG2L->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES1     ;
    MOVFF   PRODL, RES0     ;
;
    MOVF    ARG1H, W
    MULWF   ARG2H           ; ARG1H * ARG2H->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES3     ;
    MOVFF   PRODL, RES2     ;
;
    MOVF    ARG1L, W
    MULWF   ARG2H           ; ARG1L * ARG2H->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
;
    MOVF    ARG1H,  W       ;
    MULWF   ARG2L           ; ARG1H * ARG2L->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
```

Example 7-4 shows the sequence to do a 16 x 16 signed multiply. Equation 7-2 shows the algorithm used. The 32-bit result is stored in four registers (RES3:RES0). To account for the signed bits of the arguments, the MSb for each argument pair is tested and the appropriate subtractions are done.

EQUATION 7-2: 16 x 16 SIGNED MULTIPLICATION ALGORITHM

$$
\begin{aligned}
RES3:RES0 &= ARG1H:ARG1L \bullet ARG2H:ARG2L \\
&= (ARG1H \bullet ARG2H \bullet 2^{16}) + \\
&\quad (ARG1H \bullet ARG2L \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2H \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2L) + \\
&\quad (-1 \bullet ARG2H\langle 7\rangle \bullet ARG1H:ARG1L \bullet 2^{16}) + \\
&\quad (-1 \bullet ARG1H\langle 7\rangle \bullet ARG2H:ARG2L \bullet 2^{16})
\end{aligned}
$$

EXAMPLE 7-4: 16 x 16 SIGNED MULTIPLY ROUTINE

```
    MOVF    ARG1L, W
    MULWF   ARG2L           ; ARG1L * ARG2L ->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES1     ;
    MOVFF   PRODL, RES0     ;
;
    MOVF    ARG1H, W
    MULWF   ARG2H           ; ARG1H * ARG2H ->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES3     ;
    MOVFF   PRODL, RES2     ;
;
    MOVF    ARG1L, W
    MULWF   ARG2H           ; ARG1L * ARG2H ->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
;
    MOVF    ARG1H, W        ;
    MULWF   ARG2L           ; ARG1H * ARG2L ->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
;
    BTFSS   ARG2H, 7        ; ARG2H:ARG2L neg?
    BRA     SIGN_ARG1       ; no, check ARG1
    MOVF    ARG1L, W        ;
    SUBWF   RES2            ;
    MOVF    ARG1H, W        ;
    SUBWFB  RES3
;
SIGN_ARG1
    BTFSS   ARG1H, 7        ; ARG1H:ARG1L neg?
    BRA     CONT_CODE       ; no, done
    MOVF    ARG2L, W        ;
    SUBWF   RES2            ;
    MOVF    ARG2H, W        ;
    SUBWFB  RES3
;
CONT_CODE
   :
```

8.0 INTERRUPTS

The PIC18F6390/6490/8390/8490 devices have multiple interrupt sources and an interrupt priority feature that allows most interrupt sources to be assigned a high-priority level or a low-priority level. The high-priority interrupt vector is at 0008h and the low-priority interrupt vector is at 0018h. High-priority interrupt events will interrupt any low-priority interrupts that may be in progress.

There are thirteen registers which are used to control interrupt operation. These registers are:

- RCON
- INTCON
- INTCON2
- INTCON3
- PIR1, PIR2, PIR3
- PIE1, PIE2, PIE3
- IPR1, IPR2, IPR3

It is recommended that the Microchip header files supplied with MPLAB® IDE be used for the symbolic bit names in these registers. This allows the assembler/compiler to automatically take care of the placement of these bits within the specified register.

In general, interrupt sources have three bits to control their operation. They are:

- **Flag bit** to indicate that an interrupt event occurred
- **Enable bit** that allows program execution to branch to the interrupt vector address when the flag bit is set
- **Priority bit** to select high priority or low priority

The interrupt priority feature is enabled by setting the IPEN bit (RCON<7>). When interrupt priority is enabled, there are two bits which enable interrupts globally. Setting the GIEH bit (INTCON<7>) enables all interrupts that have the priority bit set (high priority). Setting the GIEL bit (INTCON<6>) enables all interrupts that have the priority bit cleared (low priority). When the interrupt flag, enable bit and appropriate global interrupt enable bit are set, the interrupt will vector immediately to address 0008h or 0018h, depending on the priority bit setting. Individual interrupts can be disabled through their corresponding enable bits.

When the IPEN bit is cleared (default state), the interrupt priority feature is disabled and interrupts are compatible with PIC® mid-range devices. In Compatibility mode, the interrupt priority bits for each source have no effect. INTCON<6> is the PEIE bit, which enables/disables all peripheral interrupt sources. INTCON<7> is the GIE bit, which enables/disables all interrupt sources. All interrupts branch to address 0008h in Compatibility mode.

When an interrupt is responded to, the global interrupt enable bit is cleared to disable further interrupts. If the IPEN bit is cleared, this is the GIE bit. If interrupt priority levels are used, this will be either the GIEH or GIEL bit. High-priority interrupt sources can interrupt a low-priority interrupt. Low-priority interrupts are not processed while high-priority interrupts are in progress.

The return address is pushed onto the stack and the PC is loaded with the interrupt vector address (0008h or 0018h). Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bits must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

The “return from interrupt” instruction, `RETFIE`, exits the interrupt routine and sets the GIE bit (GIEH or GIEL if priority levels are used), which re-enables interrupts.

For external interrupt events, such as the INTx pins or the PORTB input change interrupt, the interrupt latency will be three to four instruction cycles. The exact latency is the same for one or two-cycle instructions. Individual interrupt flag bits are set, regardless of the status of their corresponding enable bit or the GIE bit.

Note:	Do not use the `MOVFF` instruction to modify any of the interrupt control registers while **any** interrupt is enabled. Doing so may cause erratic microcontroller behavior.

8.1 INTCON Registers

The INTCON registers are readable and writable registers which contain various enable, priority and flag bits.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global interrupt enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

REGISTER 8-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GIE/GIEH:** Global Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked interrupts
0 = Disables all interrupts
When IPEN = 1:
1 = Enables all high-priority interrupts
0 = Disables all interrupts

bit 6 **PEIE/GIEL:** Peripheral Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts
When IPEN = 1:
1 = Enables all low-priority peripheral interrupts
0 = Disables all low-priority peripheral interrupts

bit 5 **TMR0IE:** TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 overflow interrupt
0 = Disables the TMR0 overflow interrupt

bit 4 **INT0IE:** INT0 External Interrupt Enable bit
1 = Enables the INT0 external interrupt
0 = Disables the INT0 external interrupt

bit 3 **RBIE:** RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2 **TMR0IF:** TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INT0IF:** INT0 External Interrupt Flag bit
1 = The INT0 external interrupt occurred (must be cleared in software)
0 = The INT0 external interrupt did not occur

bit 0 **RBIF:** RB Port Change Interrupt Flag bit(1)
1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)
0 = None of the RB7:RB4 pins have changed state

Note 1: A mismatch condition will continue to set this bit. Reading PORTB will end the mismatch condition and allow the bit to be cleared.

9.9 PORTJ, TRISJ and LATJ Registers

Note: PORTJ is available only on 80-pin devices.

PORTJ is an 8-bit wide, bidirectional port. The corresponding Data Direction register is TRISJ. Setting a TRISJ bit (= 1) will make the corresponding PORTJ pin an input (i.e., put the corresponding output driver in a high-impedance mode). Clearing a TRISJ bit (= 0) will make the corresponding PORTJ pin an output (i.e., put the contents of the output latch on the selected pin).

The Data Latch register (LATJ) is also memory mapped. Read-modify-write operations on the LATJ register read and write the latched output value for PORTJ.

All pins on PORTJ are implemented with Schmitt Trigger input buffers. Each pin is individually configurable as an input or output.

Note: On a Power-on Reset, these pins are configured as digital inputs.

PORTJ is also multiplexed with LCD segment drives controlled by the LCDSE4 register. I/O port functions are only available when the segments are disabled.

EXAMPLE 9-9: INITIALIZING PORTJ

```
CLRF    PORTJ    ; Initialize PORTG by
                 ; clearing output
                 ; data latches
CLRF    LATJ     ; Alternate method
                 ; to clear output
                 ; data latches
MOVLW 0xCF       ; Value used to
                 ; initialize data
                 ; direction
MOVWF TRISJ      ; Set RJ3:RJ0 as inputs
                 ; RJ5:RJ4 as output
                 ; RJ7:RJ6 as inputs
```

14.0 CAPTURE/COMPARE/PWM (CCP) MODULES

PIC18F6390/6490/8390/8490 devices have two CCP (Capture/Compare/PWM) modules, designated CCP1 and CCP2. Both modules implement standard capture, compare and Pulse-Width Modulation (PWM) modes.

Each CCP module contains a 16-bit register which can operate as a 16-bit Capture register, a 16-bit Compare register or a PWM Master/Slave Duty Cycle register. For the sake of clarity, all CCP module operation in the following sections is described with respect to CCP2, but is equally applicable to CCP1.

REGISTER 14-1: CCPxCON: CCPx CONTROL REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DCxB1	DCxB0	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DCxB1:DCxB0**: PWM Duty Cycle bit 1 and bit 0 for CCPx Module

Capture mode:
Unused.

Compare mode:
Unused.

PWM mode:
These bits are the two Least Significant bits (bit 1 and bit 0) of the 10-bit PWM duty cycle. The eight Most Significant bits (DCxB9:DCxB2) of the duty cycle are found in CCPRxL.

bit 3-0 **CCPxM3:CCPxM0**: CCPx Module Mode Select bits

0000 = Capture/Compare/PWM disabled (resets CCPx module)
0001 = Reserved
0010 = Compare mode, toggle output on match (CCPxIF bit is set)
0011 = Reserved
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode: initialize CCPx pin low; on compare match, force CCPx pin high (CCPxIF bit is set)
1001 = Compare mode: initialize CCPx pin high; on compare match, force CCPx pin low (CCPxIF bit is set)
1010 = Compare mode: generate software interrupt on compare match (CCPxIF bit is set, CCPx pin reflects I/O state)
1011 = Compare mode: trigger special event, reset timer, start A/D conversion on CCPx match (CCPxIF bit is set)**(1)**
11xx = PWM mode

Note 1: CCPxM3:CCPxM0 = 1011 will only reset the timer and not start the A/D conversion on the CCPx match.

15.4.10 I²C MASTER MODE TRANSMISSION

Transmission of a data byte, a 7-bit address or the other half of a 10-bit address is accomplished by simply writing a value to the SSPBUF register. This action will set the Buffer Full flag bit, BF, and allow the Baud Rate Generator to begin counting and start the next transmission. Each bit of address/data will be shifted out onto the SDA pin after the falling edge of SCL is asserted (see data hold time specification parameter #106). SCL is held low for one Baud Rate Generator rollover count (TBRG). Data should be valid before SCL is released high (see data setup time specification parameter #107). When the SCL pin is released high, it is held that way for TBRG. The data on the SDA pin must remain stable for that duration and some hold time after the next falling edge of SCL. After the eighth bit is shifted out (the falling edge of the eighth clock), the BF flag is cleared and the master releases SDA. This allows the slave device being addressed to respond with an $\overline{ACK}$ bit during the ninth bit time if an address match occurred, or if data was received properly. The status of $\overline{ACK}$ is written into the ACKDT bit on the falling edge of the ninth clock. If the master receives an Acknowledge, the Acknowledge Status bit, ACKSTAT, is cleared. If not, the bit is set. After the ninth clock, the SSPIF bit is set and the master clock (Baud Rate Generator) is suspended until the next data byte is loaded into the SSPBUF, leaving SCL low and SDA unchanged (Figure 15-21).

After the write to the SSPBUF, each bit of address will be shifted out on the falling edge of SCL until all 7 address bits and the $\overline{R/W}$ bit are completed. On the falling edge of the eighth clock, the master will deassert the SDA pin, allowing the slave to respond with an Acknowledge. On the falling edge of the ninth clock, the master will sample the SDA pin to see if the address was recognized by a slave. The status of the $\overline{ACK}$ bit is loaded into the ACKSTAT status bit (SSPCON2<6>). Following the falling edge of the ninth clock transmission of the address, the SSPIF is set, the BF flag is cleared and the Baud Rate Generator is turned off until another write to the SSPBUF takes place, holding SCL low and allowing SDA to float.

15.4.10.1 BF Status Flag

In Transmit mode, the BF bit (SSPSTAT<0>) is set when the CPU writes to SSPBUF and is cleared when all 8 bits are shifted out.

15.4.10.2 WCOL Status Flag

If the user writes the SSPBUF when a transmit is already in progress (i.e., SSPSR is still shifting out a data byte), the WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

WCOL must be cleared in software.

15.4.10.3 ACKSTAT Status Flag

In Transmit mode, the ACKSTAT bit (SSPCON2<6>) is cleared when the slave has sent an Acknowledge ($\overline{ACK}$ = 0) and is set when the slave does not Acknowledge ($\overline{ACK}$ = 1). A slave sends an Acknowledge when it has recognized its address (including a general call), or when the slave has properly received its data.

15.4.11 I²C MASTER MODE RECEPTION

Master mode reception is enabled by programming the Receive Enable bit, RCEN (SSPCON2<3>).

Note:	The MSSP module must be in an Idle state before the RCEN bit is set or the RCEN bit will be disregarded.

The Baud Rate Generator begins counting and on each rollover, the state of the SCL pin changes (high-to-low/low-to-high) and data is shifted into the SSPSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPSR are loaded into the SSPBUF, the BF flag bit is set, the SSPIF flag bit is set and the Baud Rate Generator is suspended from counting, holding SCL low. The MSSP is now in Idle state awaiting the next command. When the buffer is read by the CPU, the BF flag bit is automatically cleared. The user can then send an Acknowledge bit at the end of reception by setting the Acknowledge Sequence Enable bit, ACKEN (SSPCON2<4>).

15.4.11.1 BF Status Flag

In receive operation, the BF bit is set when an address or data byte is loaded into SSPBUF from SSPSR. It is cleared when the SSPBUF register is read.

15.4.11.2 SSPOV Status Flag

In receive operation, the SSPOV bit is set when 8 bits are received into the SSPSR and the BF flag bit is already set from a previous reception.

15.4.11.3 WCOL Status Flag

If the user writes the SSPBUF when a receive is already in progress (i.e., SSPSR is still shifting in a data byte), the WCOL bit is set and the contents of the buffer are unchanged (the write doesn't occur).

15.4.17.1 Bus Collision During a Start Condition

During a Start condition, a bus collision occurs if:

a) SDA or SCL are sampled low at the beginning of the Start condition (Figure 15-26).

b) SCL is sampled low before SDA is asserted low (Figure 15-27).

During a Start condition, both the SDA and the SCL pins are monitored.

If the SDA pin is already low, or the SCL pin is already low, then all of the following occur:

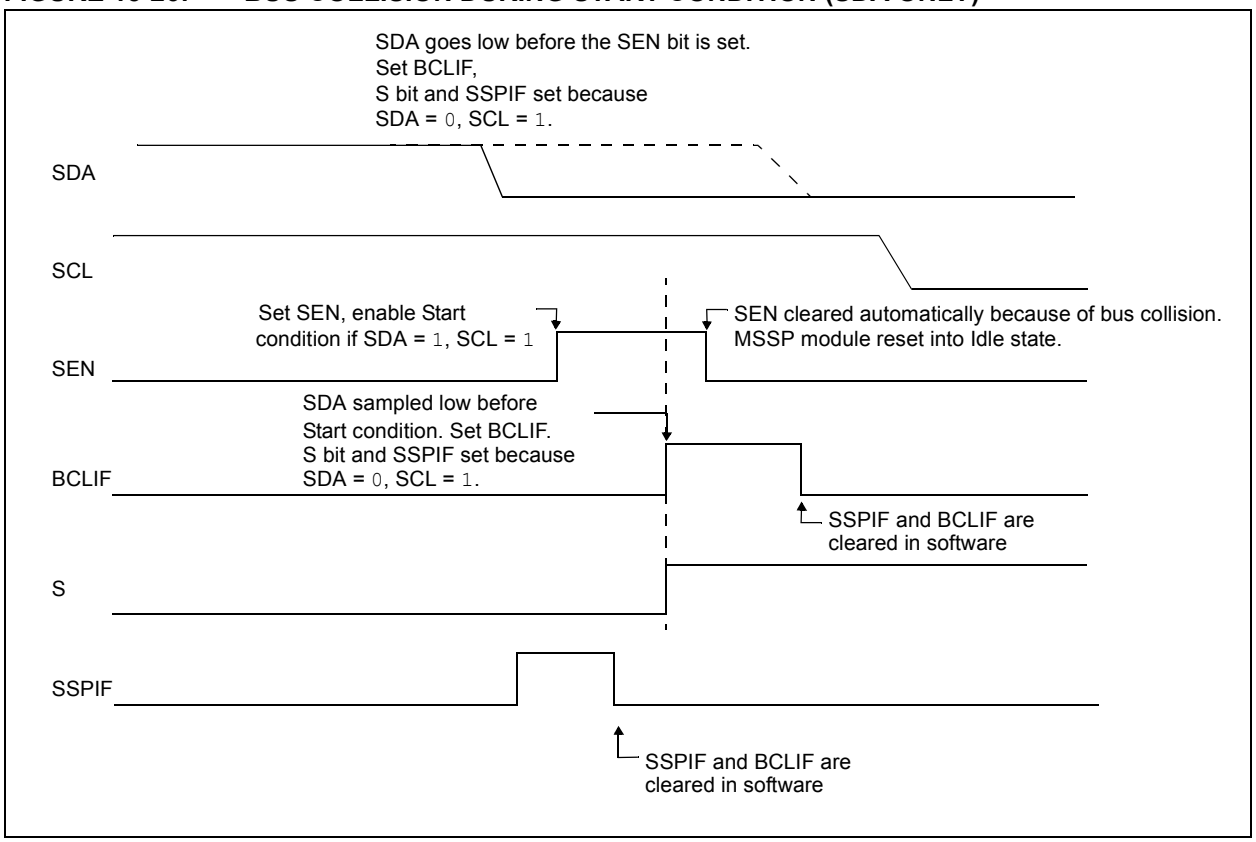
- the Start condition is aborted,
- the BCLIF flag is set and
- the MSSP module is reset to its Idle state (Figure 15-26).

The Start condition begins with the SDA and SCL pins deasserted. When the SDA pin is sampled high, the Baud Rate Generator is loaded from SSPADD<6:0> and counts down to '0'. If the SCL pin is sampled low while SDA is high, a bus collision occurs because it is assumed that another master is attempting to drive a data '1' during the Start condition.

If the SDA pin is sampled low during this count, the BRG is reset and the SDA line is asserted early (Figure 15-28). If, however, a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The Baud Rate Generator is then reloaded and counts down to 0 and during this time, if the SCL pins are sampled as '0', a bus collision does not occur. At the end of the BRG count, the SCL pin is asserted low.

Note:	The reason that bus collision is not a factor during a Start condition is that no two bus masters can assert a Start condition at the exact same time. Therefore, one master will always assert SDA before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the Start condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start or Stop conditions.

FIGURE 15-26: BUS COLLISION DURING START CONDITION (SDA ONLY)



16.4.2 EUSART SYNCHRONOUS SLAVE RECEPTION

The operation of the Synchronous Master and Slave modes is identical except in the case of Sleep or any Idle mode and bit, SREN, which is a “don’t care” in Slave mode.

If receive is enabled by setting the CREN bit prior to entering Sleep or any Idle mode, then a word may be received while in this low-power mode. Once the word is received, the RSR register will transfer the data to the RCREG1 register. If the RC1IE enable bit is set, the interrupt generated will wake the chip from the low-power mode. If the global interrupt is enabled, the program will branch to the interrupt vector.

To set up a Synchronous Slave Reception:

1. Enable the synchronous master serial port by setting bits, SYNC and SPEN, and clearing bit, CSRC.
2. If interrupts are desired, set enable bit, RC1IE.
3. If 9-bit reception is desired, set bit, RX9.
4. To enable reception, set enable bit, CREN.
5. Flag bit, RC1IF, will be set when reception is complete. An interrupt will be generated if enable bit, RC1IE, was set.
6. Read the RCSTA1 register to get the 9th bit (if enabled) and determine if any error occurred during reception.
7. Read the 8-bit received data by reading the RCREG1 register.
8. If any error occurred, clear the error by clearing bit, CREN.
9. If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

TABLE 16-10: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	59
PIR1	—	ADIF	RC1IF	TX1IF	SSPIF	CCP1IF	TMR2IF	TMR1IF	61
PIE1	—	ADIE	RC1IE	TX1IE	SSPIE	CCP1IE	TMR2IE	TMR1IE	61
IPR1	—	ADIP	RC1IP	TX1IP	SSPIP	CCP1IP	TMR2IP	TMR1IP	61
RCSTA1	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	61
RCREG1	EUSART1 Receive Register								61
TXSTA1	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	61
BAUDCON1	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	62
SPBRGH1	EUSART1 Baud Rate Generator Register High Byte								62
SPBRG1	EUSART1 Baud Rate Generator Register Low Byte								61

Legend: — = unimplemented, read as ‘0’. Shaded cells are not used for synchronous slave reception.

17.3.2 AUSART SYNCHRONOUS MASTER RECEPTION

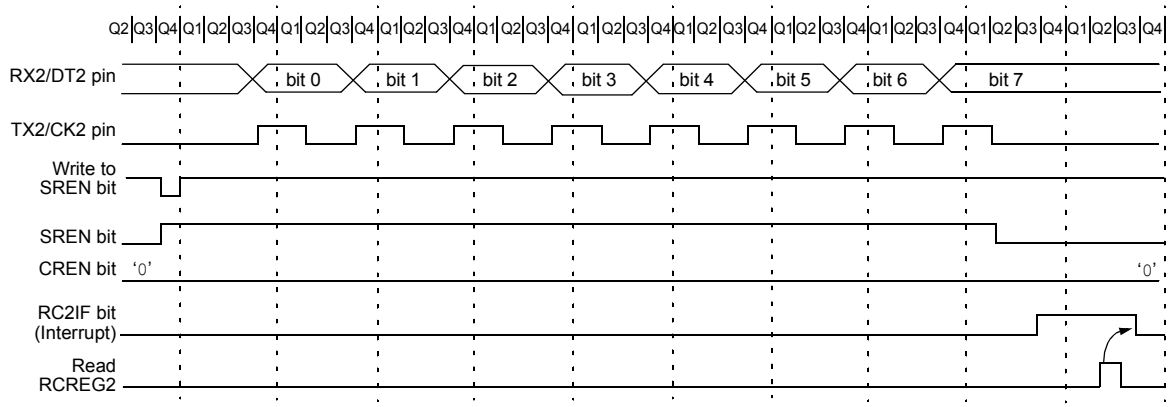
Once Synchronous mode is selected, reception is enabled by setting either the Single Receive Enable bit, SREN (RCSTA2<5>), or the Continuous Receive Enable bit, CREN (RCSTA2<4>). Data is sampled on the RX2 pin on the falling edge of the clock.

If enable bit, SREN, is set, only a single word is received. If enable bit, CREN, is set, the reception is continuous until CREN is cleared. If both bits are set, then CREN takes precedence.

To set up a Synchronous Master Reception:

1. Initialize the SPBRG2 register for the appropriate baud rate.
2. Enable the synchronous master serial port by setting bits, SYNC, SPEN and CSRC.
3. Ensure bits, CREN and SREN, are clear.
4. If interrupts are desired, set enable bit, RC2IE.
5. If 9-bit reception is desired, set bit, RX9.
6. If a single reception is required, set bit, SREN. For continuous reception, set bit, CREN.
7. Interrupt flag bit, RC2IF, will be set when reception is complete and an interrupt will be generated if the enable bit, RC2IE, was set.
8. Read the RCSTA2 register to get the 9th bit (if enabled) and determine if any error occurred during reception.
9. Read the 8-bit received data by reading the RCREG2 register.
10. If any error occurred, clear the error by clearing bit, CREN.
11. If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

FIGURE 17-8: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



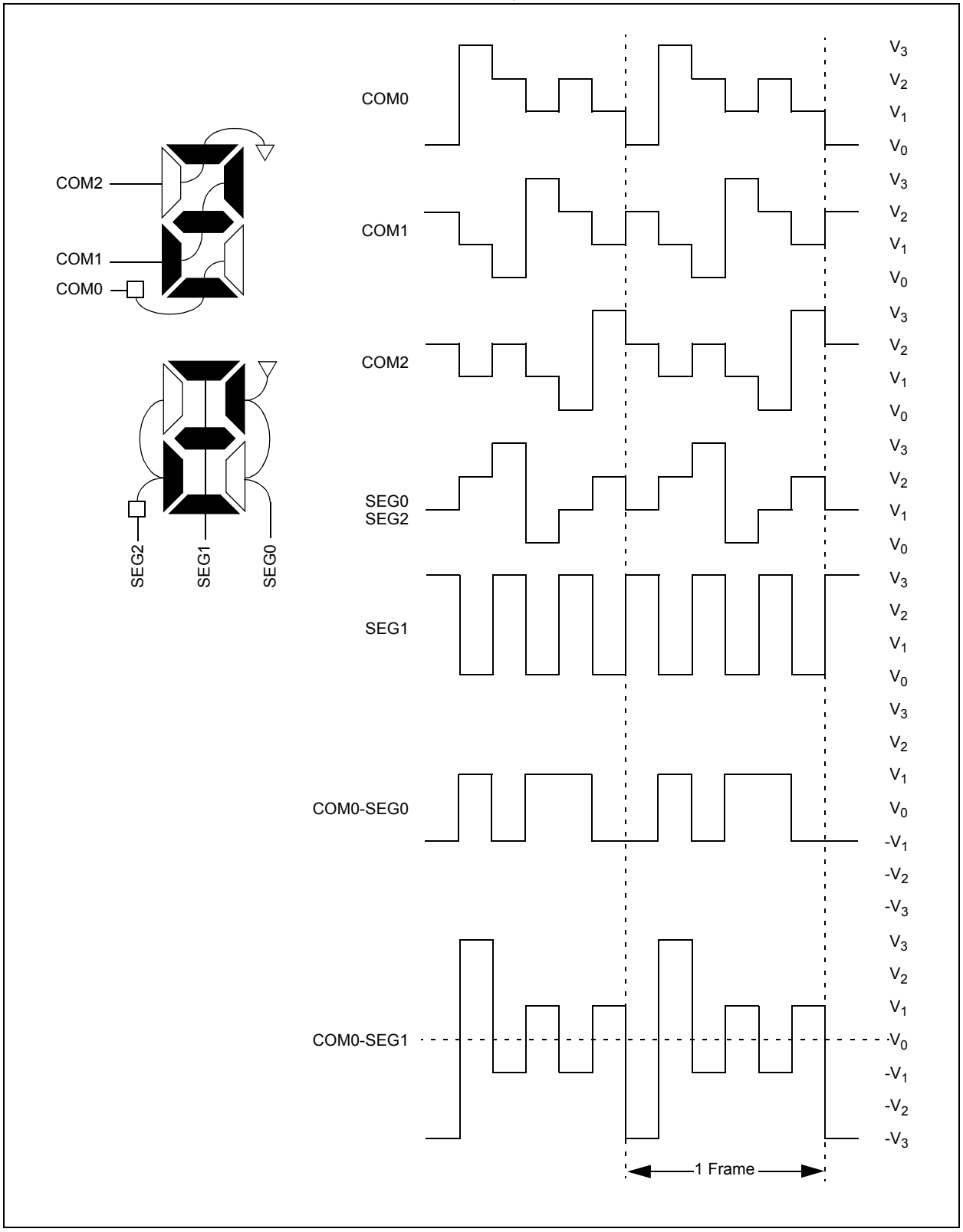
Note: Timing diagram demonstrates Sync Master mode with bit SREN = 1 and bit BRGH = 0.

TABLE 17-7: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	59
PIR3	—	LCDIF	RC2IF	TX2IF	—	—	—	—	61
PIE3	—	LCDIE	RC2IE	TX2IE	—	—	—	—	61
IPR3	—	LCDIP	RC2IP	TX2IP	—	—	—	—	61
RCSTA2	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	63
RCREG2	AUSART2 Receive Register								63
TXSTA2	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	63
SPBRG2	AUSART2 Baud Rate Generator Register								63

Legend: — = unimplemented, read as '0'. Shaded cells are not used for synchronous master reception.

FIGURE 22-11: TYPE-A WAVEFORMS IN 1/3 MUX, 1/3 BIAS DRIVE



ADDWFC **ADD W and Carry bit to f**

Syntax: ADDWFC f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (W) + (f) + (C) → dest

Status Affected: N,OV, C, DC, Z

Encoding:

0010	00da	ffff	ffff

Description: Add W, the Carry flag and data memory location 'f'. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in data memory location 'f'.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `ADDWFC REG, 0, 1`

Before Instruction
Carry bit = 1
REG = 02h
W = 4Dh
After Instruction
Carry bit = 0
REG = 02h
W = 50h

ANDLW **AND Literal with W**

Syntax: ANDLW k

Operands: $0 \le k \le 255$

Operation: (W) .AND. k → W

Status Affected: N, Z

Encoding:

0000	1011	kkkk	kkkk

Description: The contents of W are ANDed with the 8-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example: `ANDLW 05Fh`

Before Instruction
W = A3h
After Instruction
W = 03h

26.1 DC Characteristics: Supply Voltage PIC18F6390/6490/8390/8490 (Industrial) PIC18LF6390/6490/8390/8490 (Industrial)

PIC18LF6390/6490/8390/8490 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18F6390/6490/8390/8490 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					
		PIC18LF6390/6490/8390/8490	2.0	—	5.5	V	HS, XT, RC and LP Oscillator modes
		PIC18F6390/6490/8390/8490	4.2	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage(1)**	1.5	—	—	V	
D003	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	0.7	V	See section on Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	See section on Power-on Reset for details
	VBOR	**Brown-out Reset Voltage**					
D005		PIC18LF6390/6490/8390/8490					
		BORV1:BORV0 = 11	2.00	2.05	2.16	V	
		BORV1:BORV0 = 10	2.65	2.79	2.93	V	
D005		All devices					
		BORV1:BORV0 = 01	4.11	4.33	4.55	V	
		BORV1:BORV0 = 00	4.36	4.59	4.82	V	

Legend: Shading of rows is to assist in readability of the table.

Note 1: This is the limit to which VDD can be lowered in Sleep mode, or during a device Reset, without losing RAM data.

26.2 DC Characteristics: Power-Down and Supply Current PIC18F6390/6490/8390/8490 (Industrial) PIC18LF6390/6490/8390/8490 (Industrial) (Continued)

PIC18LF6390/6490/8390/8490 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F6390/6490/8390/8490 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	PIC18LF6390/6490/8390/8490	12	26	µA	-40°C	VDD = 2.0V	FOSC = 31 kHz (**RC_RUN** mode, INTRC source)
		12	24	µA	+25°C		
		12	23	µA	+85°C		
	PIC18LF6390/6490/8390/8490	32	50	µA	-40°C	VDD = 3.0V	
		27	48	µA	+25°C		
		22	46	µA	+85°C		
	All devices	84	134	µA	-40°C	VDD = 5.0V	
		82	128	µA	+25°C		
		72	128	µA	+85°C		
	PIC18LF6390/6490/8390/8490	.26	.8	mA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**RC_RUN** mode, INTOSC source)
		.26	.8	mA	+25°C		
		.26	.8	mA	+85°C		
	PIC18LF6390/6490/8390/8490	.48	1.04	mA	-40°C	VDD = 3.0V	
		.44	.96	mA	+25°C		
		.48	.88	mA	+85°C		
	All devices	.88	1.84	mA	-40°C	VDD = 5.0V	
		.88	1.76	mA	+25°C		
		.8	1.68	mA	+85°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: Low-power Timer1 oscillator selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

26.2 DC Characteristics: Power-Down and Supply Current PIC18F6390/6490/8390/8490 (Industrial) PIC18LF6390/6490/8390/8490 (Industrial) (Continued)

PIC18LF6390/6490/8390/8490 (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F6390/6490/8390/8490 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	PIC18LF6390/6490/8390/8490	13	40	µA	-40°C	VDD = 2.0V	FOSC = 32 kHz (**SEC_RUN** mode, Timer1 as clock)(4)
		14	40	µA	+25°C		
		16	40	µA	+80°C		
	PIC18LF6390/6490/8390/8490	34	70	µA	-40°C	VDD = 3.0V	
		31	70	µA	+25°C		
		28	70	µA	+80°C		
	All devices	72	150	µA	-40°C	VDD = 5.0V	
		65	150	µA	+25°C		
		59	150	µA	+80°C		
	PIC18LF6390/6490/8390/8490	5.5	15	µA	-40°C	VDD = 2.0V	FOSC = 32 kHz (**SEC_IDLE** mode, Timer1 as clock)(4)
		5.8	15	µA	+25°C		
		6.1	18	µA	+80°C		
	PIC18LF6390/6490/8390/8490	8.2	30	µA	-40°C	VDD = 3.0V	
		8.6	30	µA	+25°C		
		8.8	35	µA	+80°C		
	All devices	13	80	µA	-40°C	VDD = 5.0V	
		13	80	µA	+25°C		
		13	85	µA	+80°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: Low-power Timer1 oscillator selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

26.4.3 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 26-5: EXTERNAL CLOCK TIMING (ALL MODES EXCEPT PLL)

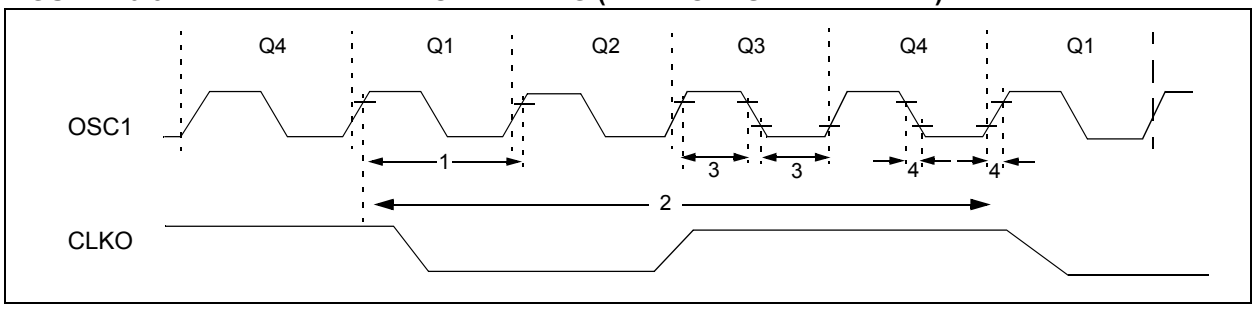


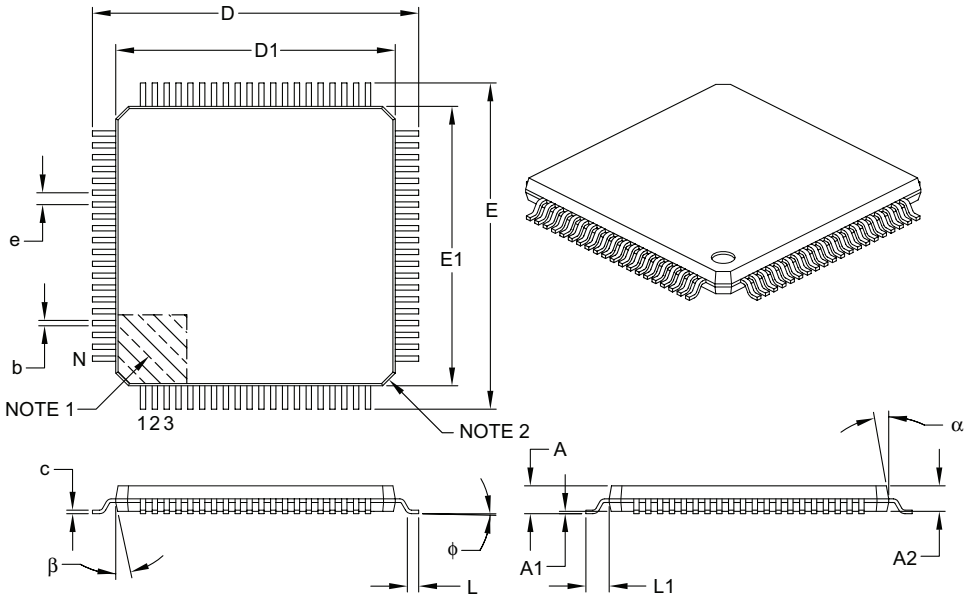
TABLE 26-6: EXTERNAL CLOCK TIMING REQUIREMENTS

Param. No.	Symbol	Characteristic	Min	Max	Units	Conditions
1A	FOSC	External CLKI Frequency(1)	DC	1	MHz	XT, RC Oscillator mode
			DC	20	MHz	HS Oscillator mode
			DC	31.25	kHz	LP Oscillator mode
		Oscillator Frequency(1)	DC	4	MHz	RC Oscillator mode
			0.1	4	MHz	XT Oscillator mode
			4	20	MHz	HS Oscillator mode
			5	200	kHz	LP Oscillator mode
1	TOSC	External CLKI Period(1)	1000	—	ns	XT, RC Oscillator mode
			50	—	ns	HS Oscillator mode
			32	—	µs	LP Oscillator mode
		Oscillator Period(1)	250	—	ns	RC Oscillator mode
			250	1	µs	XT Oscillator mode
			100	250	ns	HS Oscillator mode
			50	250	ns	HS Oscillator mode
			5	—	µs	LP Oscillator mode
2	TCY	Instruction Cycle Time(1)	100	—	ns	TCY = 4/FOSC
3	TOSL, TOSH	External Clock in (OSC1) High or Low Time	30	—	ns	XT Oscillator mode
			2.5	—	µs	LP Oscillator mode
			10	—	ns	HS Oscillator mode
4	TOSR, TOSF	External Clock in (OSC1) Rise or Fall Time	—	20	ns	XT Oscillator mode
			—	50	ns	LP Oscillator mode
			—	7.5	ns	HS Oscillator mode

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period for all configurations except PLL. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the “max.” cycle time limit is “DC” (no clock) for all devices.

80-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		80	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-092B